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Figure 1
(Prior Art)

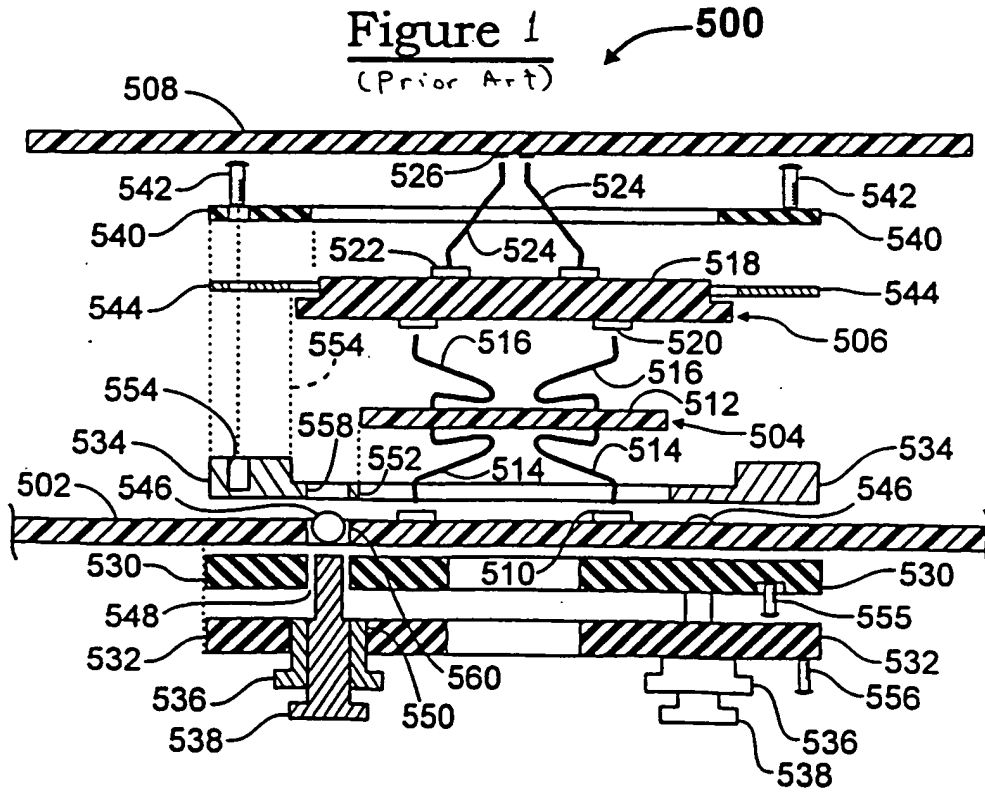


Figure 2 A
(Prior Art)

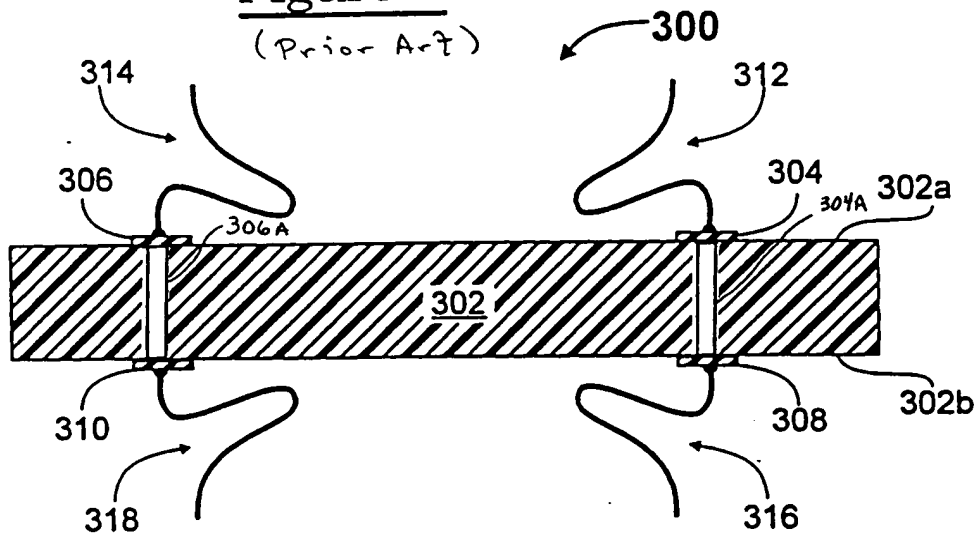


FIG. 2B (Prior Art)

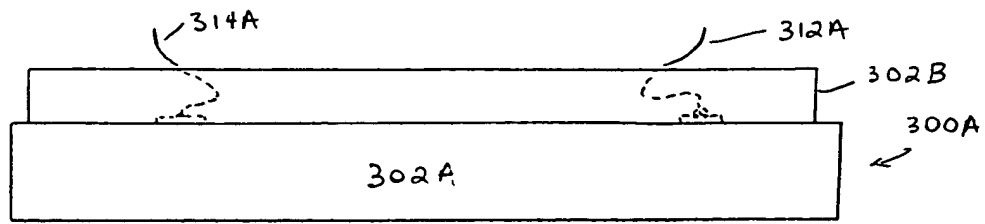


FIG. 2C (Prior Art)

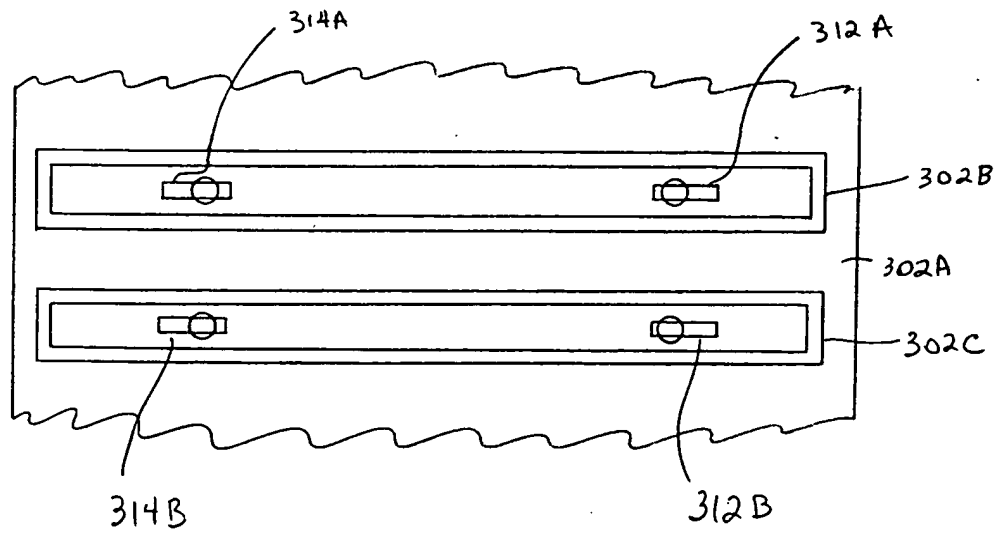


Figure 3 A (Prior Art)

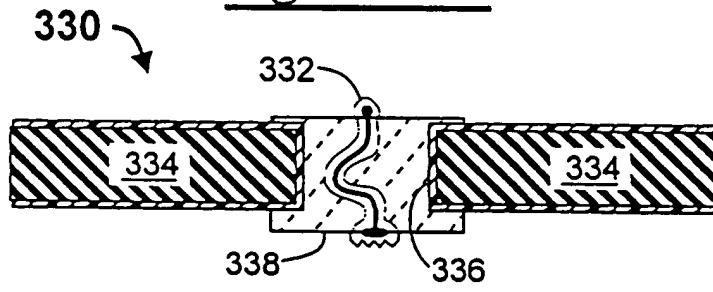


Figure 3 B (Prior Art)

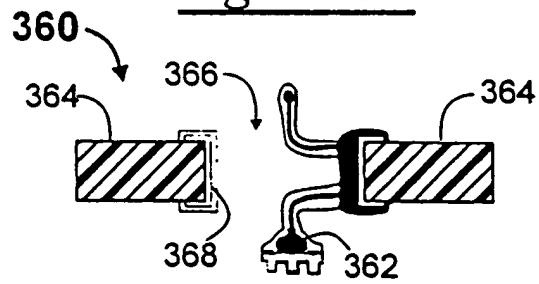


Figure 5A

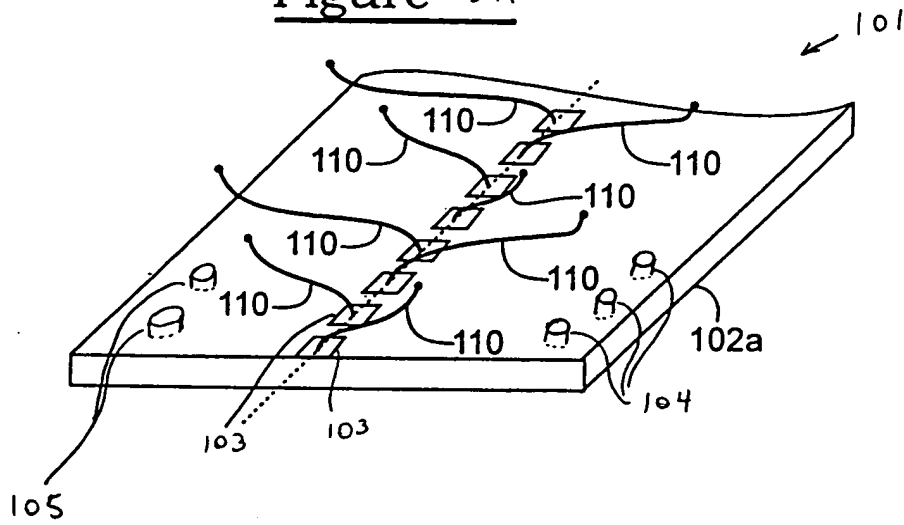


FIG. 5B

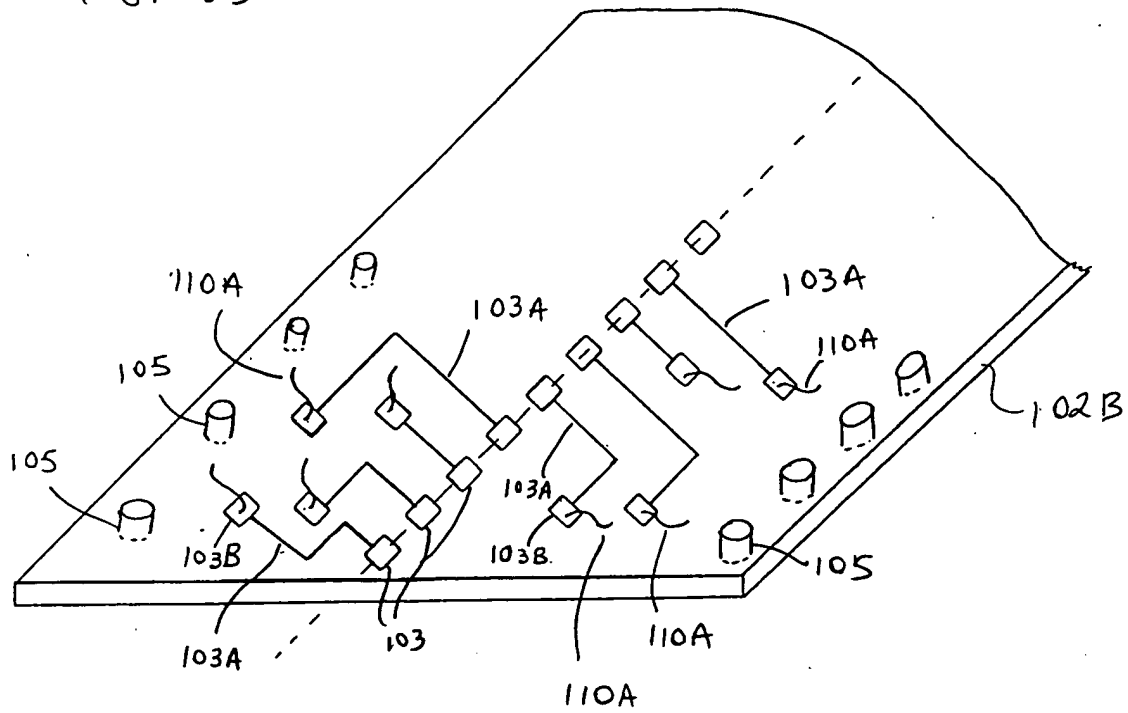


FIG. 6 A

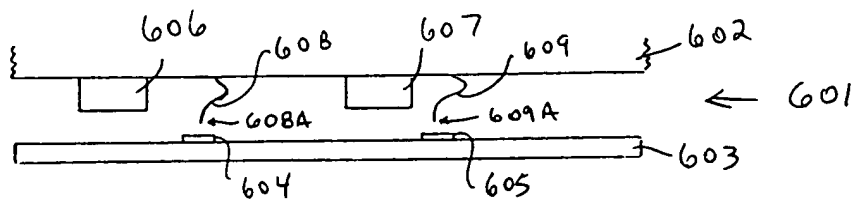


FIG. 6B

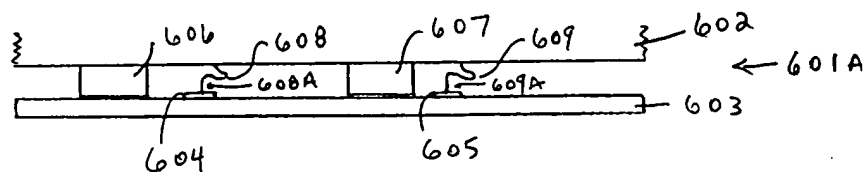


FIG. 7

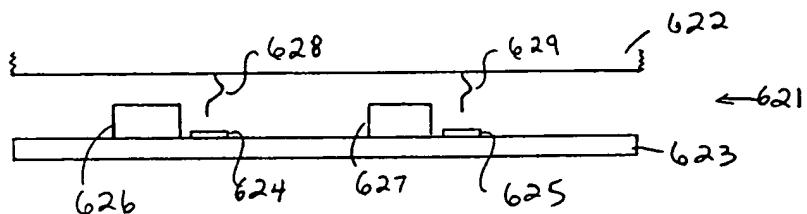


FIG. 6C

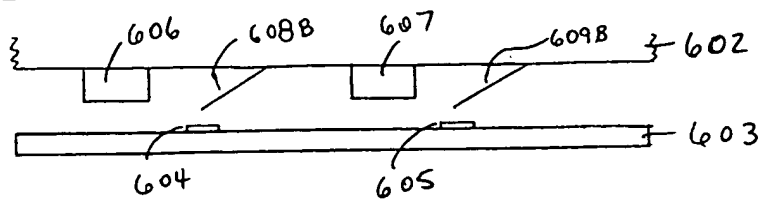


FIG. 6D

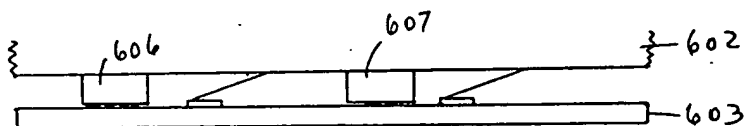


FIG. 8A

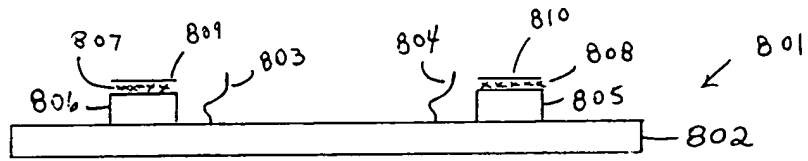


FIG. 8B

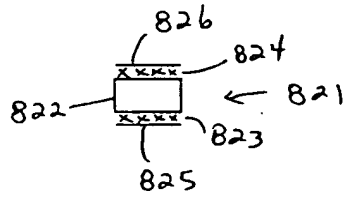


FIG. 9A

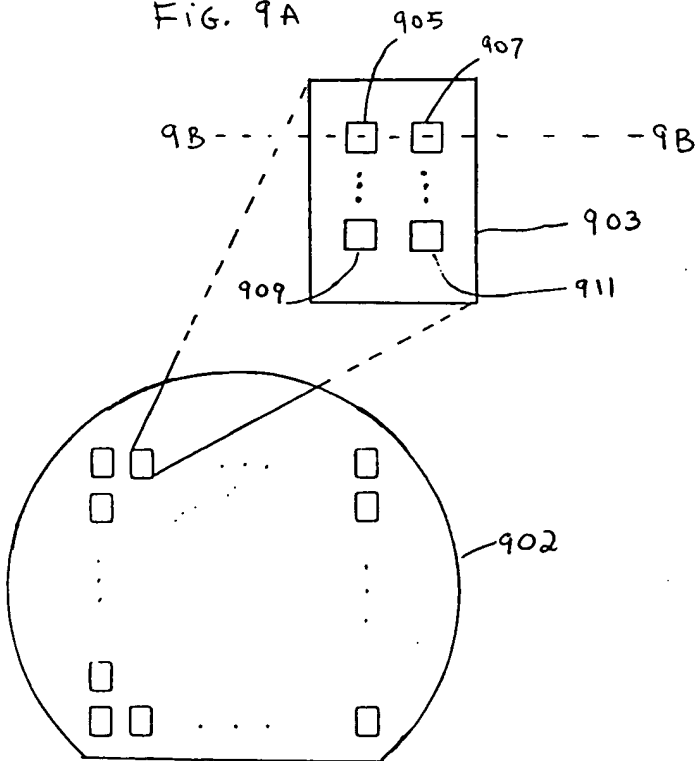


FIG. 9B

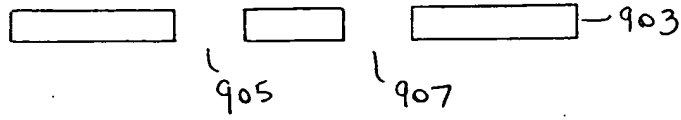


FIG. 9C

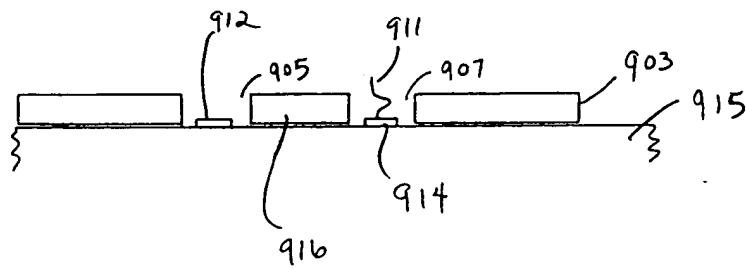


FIG. 9D

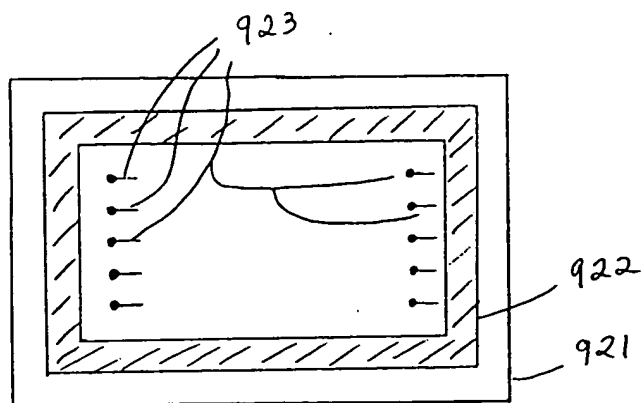


FIG. 9E

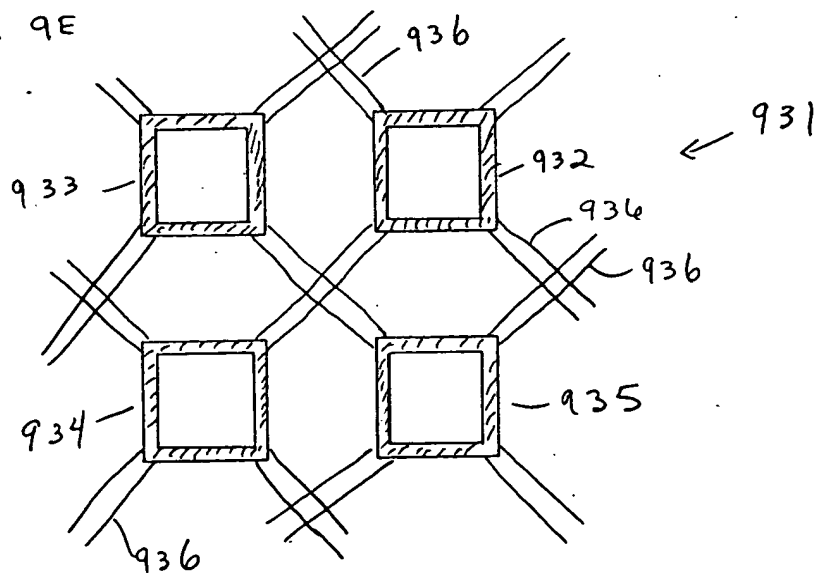


FIG. 9 F

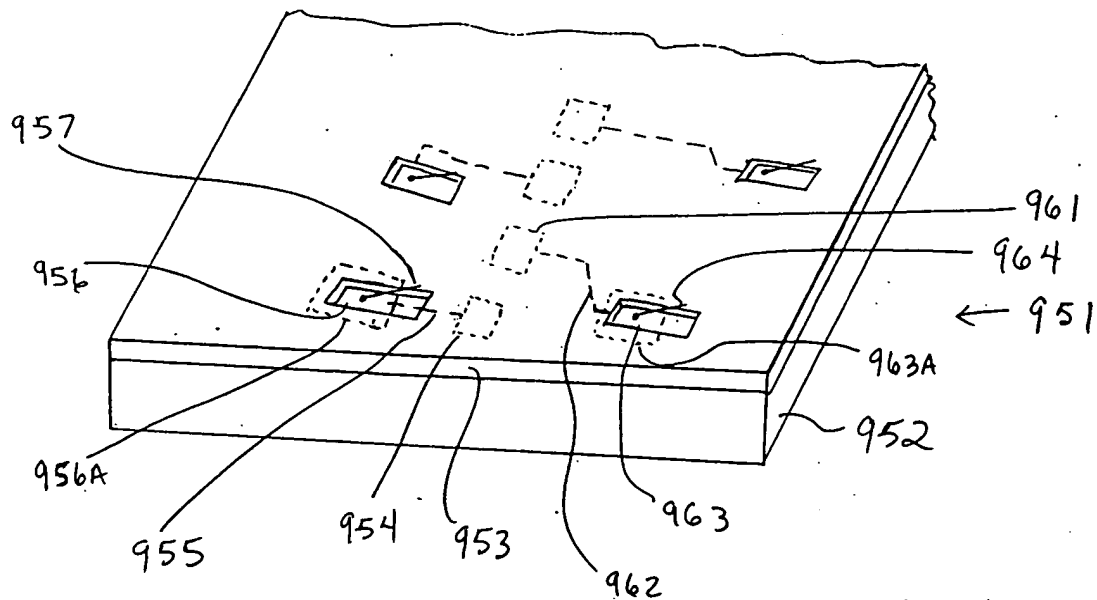


Fig. 10A

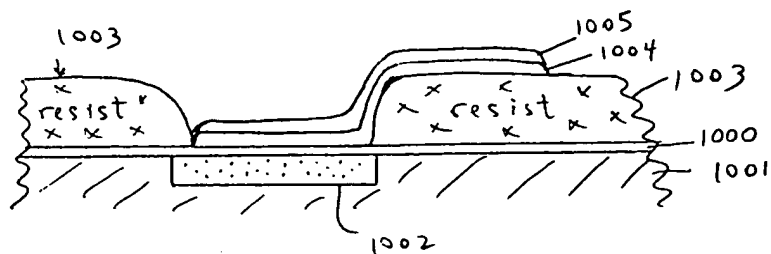


FIG 10 B

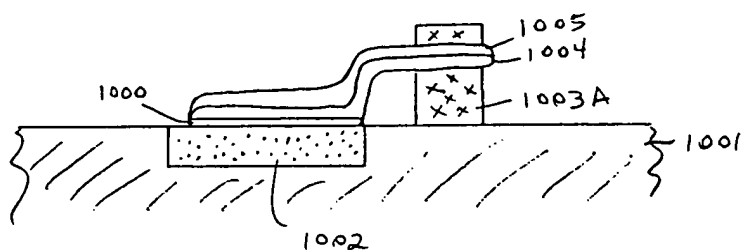
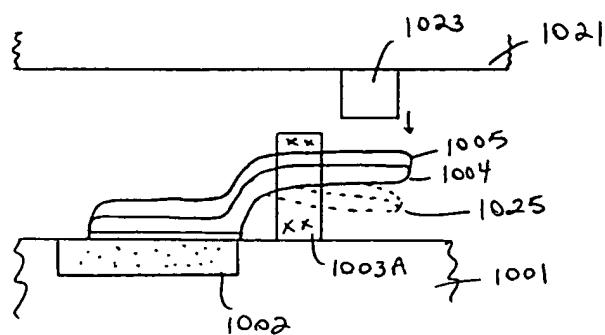


FIG. 10C



FIG. 10 D



A hand-drawn schematic diagram of a rectangular device, possibly a circuit board or a component layout. The diagram includes the following labeled parts:

- 10E**: Located at the top left corner.
- 1032**: Points to a vertical column of ten small circles on the left side.
- 1031**: Points to the top edge of the rectangle.
- 1033**: Points to a vertical column of ten small circles on the right side.
- 1041**: Points to the top right corner.
- 1040**: Points to a vertical line segment on the left side.
- 1039**: Points to a vertical line segment on the left side.
- 1035**: Points to a small circle on the right side.
- 1037**: Points to a vertical line segment on the right side.
- 1036**: Points to a small circle on the right side.
- 1038**: Points to the bottom edge of the rectangle.
- 1034**: Points to a small circle on the bottom edge.

FIG. 10 F

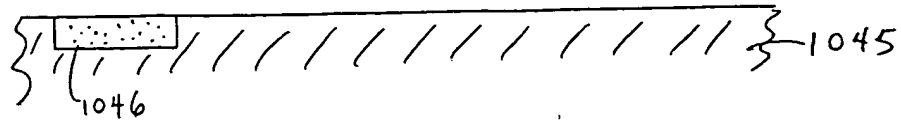


FIG. 10 G

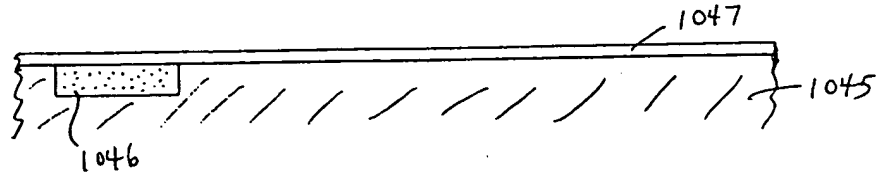


FIG. 10 H

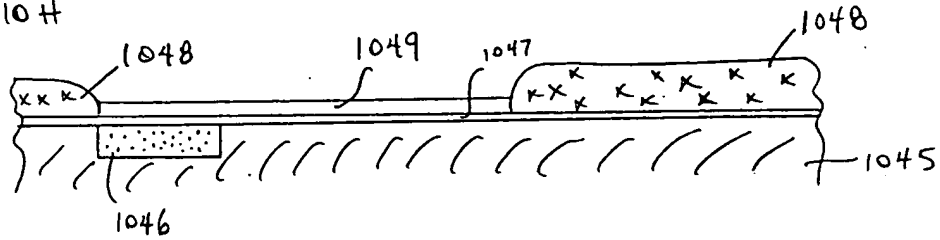


FIG. 10 I

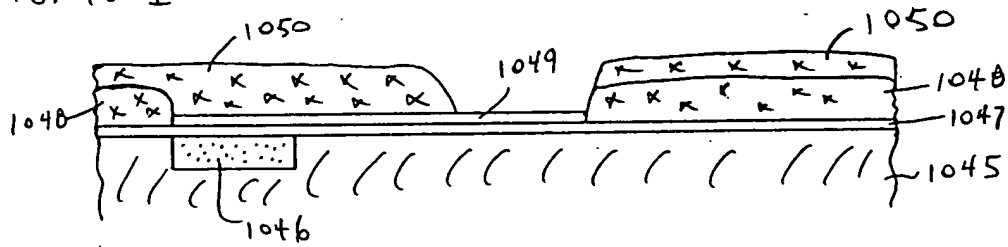


FIG. 10 J

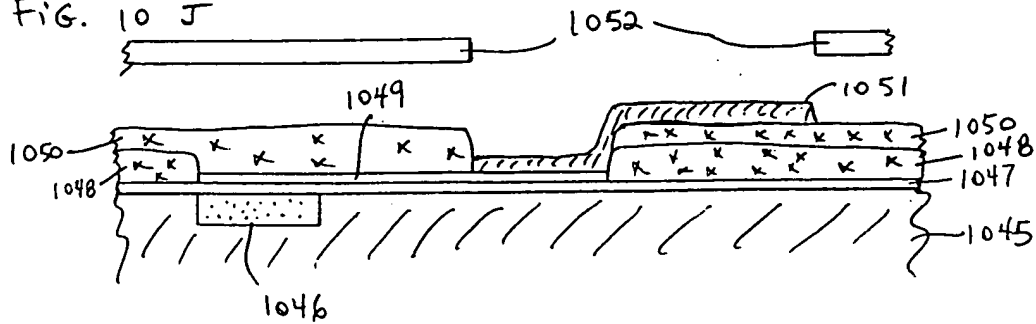


FIG. 10 K

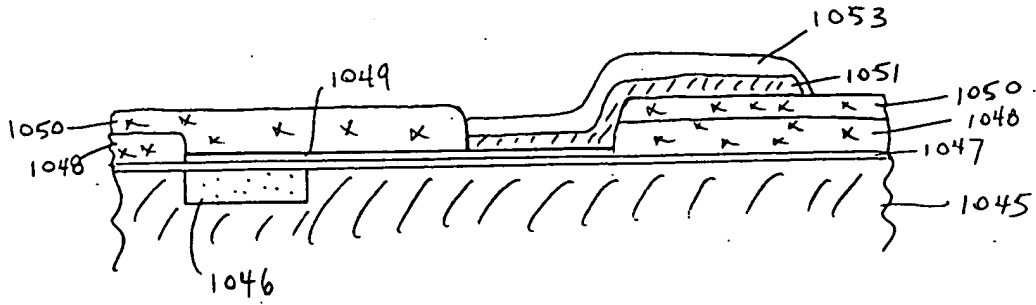


FIG. 10 L

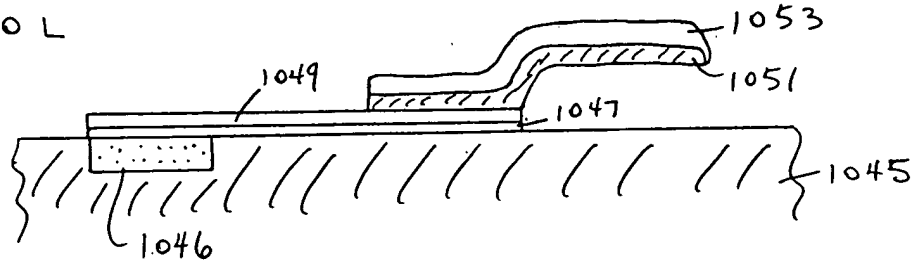


FIG. 10 M

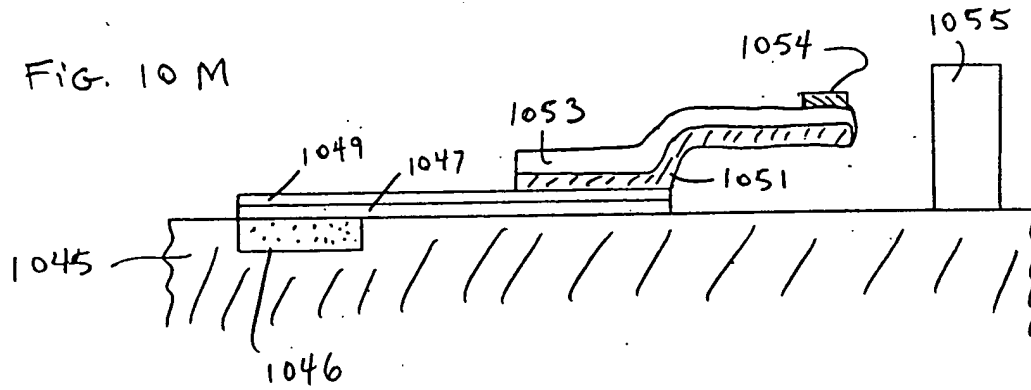


FIG. 11

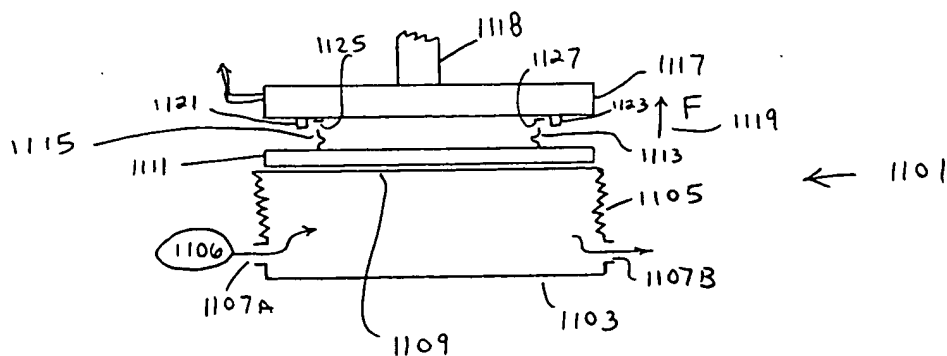


FIG. 12A

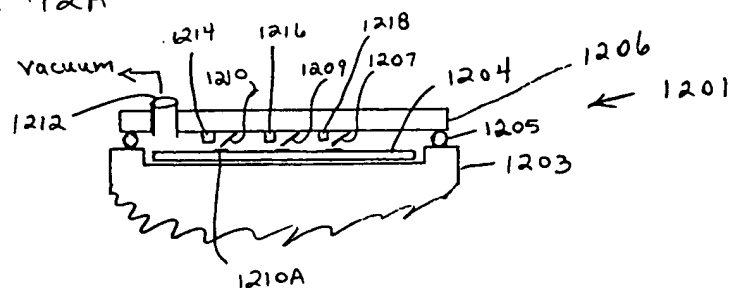
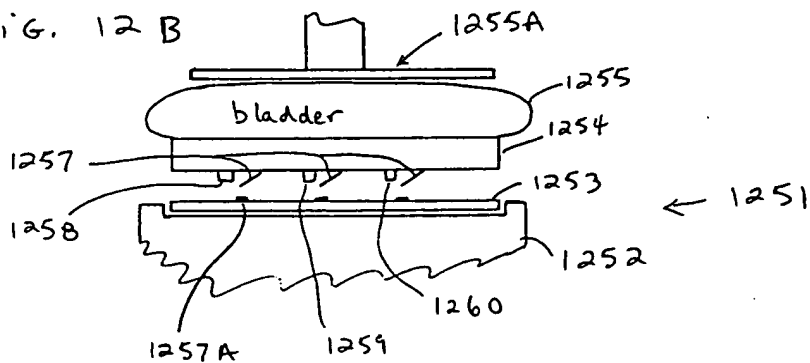


FIG. 12 B



This diagram shows a cross-sectional view of a semiconductor device. A substrate 1302 is shown with a trench 1304. A gate structure 1305 is formed on the top surface of the substrate. The trench 1304 is filled with a material 1306. A layer 1307 is formed on the bottom surface of the trench 1304. A layer 1308 is formed on the side walls of the trench 1304. A layer 1310 is formed on the top surface of the substrate 1302. A layer 1312 is formed on the top surface of the substrate 1302. A layer 1314 is formed on the top surface of the substrate 1302. A layer 1316 is formed on the top surface of the substrate 1302. A layer 1318 is formed on the top surface of the substrate 1302. A layer 1320 is formed on the top surface of the substrate 1302. A layer 1321 is formed on the top surface of the substrate 1302. A layer 1322 is formed on the top surface of the substrate 1302. A layer 134A is formed on the top surface of the substrate 1302.